



US1JDF/US1MDF

Product Summary (@ T_A = +25°C)

V _{RRM} (V)	I ₀ (A)	V _F (MAX) (V)	Ι _{R(MAX)} (μΑ)
600,1000	1	1.7	5

Description and Applications

The US1JDF and US1MDF are rectifiers packaged in the low profile D-FLAT package. Providing ultra-fast recovery time for high efficiency, this device is ideal for use in general rectification applications such as:

- Switching Mode Power Supply
- **DC-DC** Converter

1.0A SURFACE MOUNT ULTRA-FAST RECTIFIER

Features and Benefits

- **Glass Passivated Die Construction**
- Ultra-Fast Recovery Time for High Efficiency
- Surge Overload Rating to 30A Peak
- **High Current Capability**
- Low Profile Design, Package Height Less than 1.1mm
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Polarity: Cathode Band •
- Weight: 0.064 grams (Approximate)

D-FLAT



Top View

Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
US1JDF-13	Commercial	D-FLAT	10,000/Tape & Reel
US1MDF-13	Commercial	D-FLAT	10,000/Tape & Reel

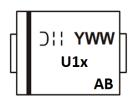
Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



U1J or U1M = Product Type Marking Code DII = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 4 for 2014) WW = Week Code (01 to 53) AB = Foundry and Assembly Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.				
Characteristic	Symbol	US1JDF	US1MDF	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)	V _{RRM} V _{RWM} V _R	600	1000	V
RMS Reverse Voltage	V _{R(RMS)}	420	700	V
Average Rectified Output Current $@T_T = +25^{\circ}C$	lo	1.0)	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30)	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 8)	$R_{\theta JT}$	44	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 8)	$R_{\theta JA}$	80	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

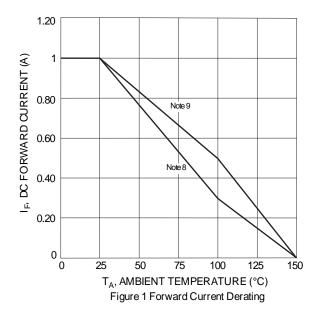
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

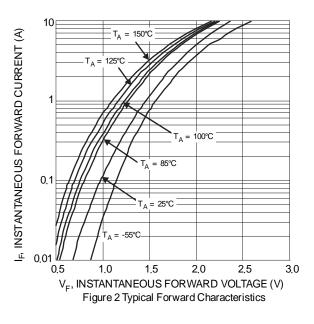
Characteristic		Symbol	US1JDF	US1MDF	Unit
Minimum Reverse Breakdown Voltage (Note 5)	@I _R = 5μA	V _{(BR)R}	600	1000	V
Maximum Forward Voltage Drop	@ I _F = 1.0A	VF	1.	7	V
Peak Reverse Current	@T _A = +25°C		5.	0	
at Rated DC Blocking Voltage (Note 5)	@T _A = +100°C	IR	10	0	μA
Maximum Reverse Recovery Time (Note 6)		t _{rr}	7	5	ns
Typical Total Capacitance (Note 7)		CT	10	D	pF

5. Short duration pulse test used to minimize self-heating effect. Notes:

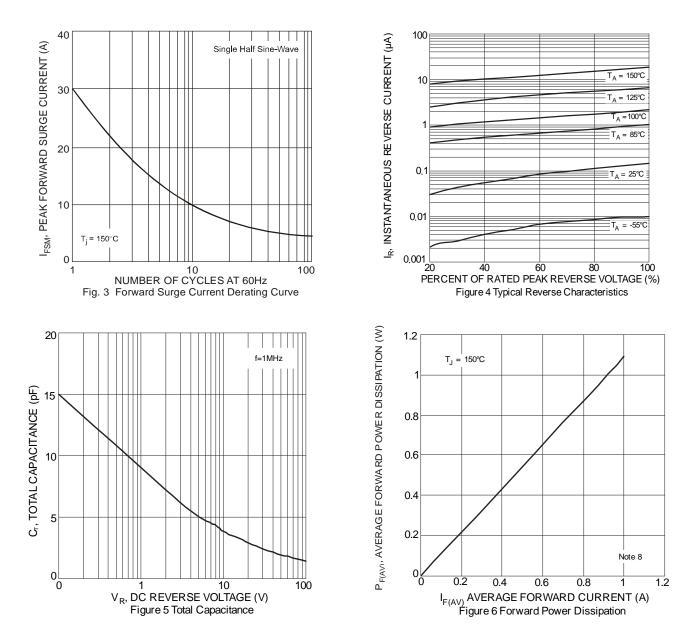
6. Measured with $I_{\rm F}$ = 0.5A, $I_{\rm R}$ = 1.0A, $I_{\rm rr}$ = 0.25A. See figure 7.

Measured with IF = 0.57, IR = 1.07, Irr = 0.257. See lighte 7.
Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
Device mounted on FR-4 substrate, 1" * 1", 2oz, single-sided, PC boards with 0.1"*0.15" copper pads.
Device mounted on FR-4 substrate, 0.4" * 0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pads.



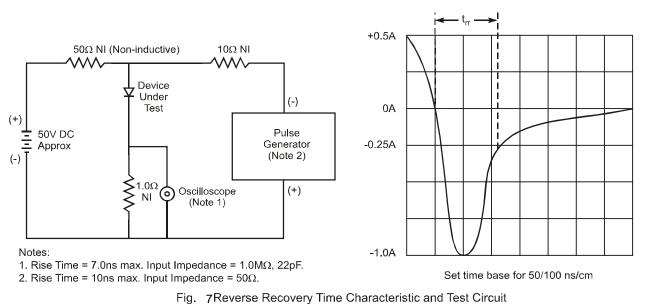






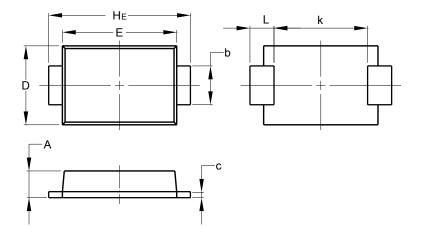


US1JDF/US1MDF



Package Outline Dimensions

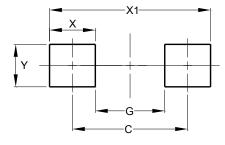
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



D-FLAT					
Dim	Min	Max			
Α	0.90	1.10			
b	1.25	1.65			
с	0.10	0.40			
D	2.25	2.95			
ш	3.95	4.60			
k	2.80	-			
HE	5.00	5.60			
L	0.50	1.30			
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	4.65
G	2.80
Х	1.85
X1	6.50
Y	1.70



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